•	2	cabl and (nanocomposite adj (material or	USPAT;	2002/08/02
		filler))	US-PGPUB;	16:16
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
	22	(nanocomposite adj (material or filler)) and	USPAT;	2002/08/02
		(conductors or wire)	US-PGPUB;	16:25
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	5089	(organic and inorganic) and cable	USPAT;	2002/08/08
		·	US-PGPUB;	19:41
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	1	(nanocomposite adj (material or filler)) and	USPAT;	2002/08/02
		((organic and inorganic) and cable)	US-PGPUB;	16:42
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	22898	power adj cable	USPAT;	2002/08/02
			US-PGPUB;	16:43
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	2	nanocomposite and (power adj cable)	USPAT;	2002/08/02
	1		US-PGPUB;	16:46
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	18	nanocomposite and cable	USPAT;	2002/08/08
			US-PGPUB;	19:41
			EPO; JPO;	
			DERWENT;	·
			IBM TDB	

L Number	Hits	Search Text	DB	Time stamp
1	5112	(organic and inorganic) and cables	USPAT;	2002/08/08
			US-PGPUB;	19:42
		·	EPO; JP ;	
			DERWENT;	
			IBM_TDB	
15	16	exfoliated and ((organic and inorganic) and	USPAT;	2002/08/08
		cables)	US-PGPUB;	19:48
		, ,	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
	202	nanacomnacita adi (material er filler)	_	2002/08/08
ia	202	nanocomposite adj (material or filler)	USPAT;	
			US-PGPUB;	19:54
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
22	60	exfoliated and (nanocomposite adj	USPAT;	2002/08/08
		(material or filler))	US-PGPUB;	19:51
			EPO; JPO;	`
			DERWENT;	
			IBM_TDB	
29	1	(exfoliated and (nanocomposite adj	USPAT;	2002/08/08
_		(material or filler))) and (cable or wire)	US-PGPUB;	19:52
		(	EPO; JPO;	10.02
			DERWENT;	
			IBM_TDB	
36	4	nanocomposite and exfoliated and (cable or	USPAT;	2002/09/09
	-	wire)	1 *	2002/08/08
		wire)	US-PGPUB;	19:55
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
43	138	nanocomposite and exfoliated	USPAT;	2002/08/08
			US-PGPUB;	20:09
			EPO; JPO;	
			DERWENT;	·
			IBM_TDB	
50	1	(nanocomposite and exfoliated ) and cable	USPAT;	2002/08/08
			US-PGPUB;	20:10
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
57	2	(nanocomposite and exfoliated ) and	USPAT;	2002/08/08
	_	semiconductor	US-PGPUB;	20:10
			EPO; JPO;	_0.10
	İ		DERWENT;	
-	204		IBM_TDB	0000/00/00
	201	nanocomposite adj (material or filler)	USPAT;	2002/08/08
			US-PGPUB;	19:48
	ĺ	:	EPO; JPO;	
			DERWENT;	
			IBM_TDB	